

Title (en)
COPPER ALLOY MATERIAL AND MANUFACTURING METHOD THEREOF

Title (de)
MATERIAL AUS KUPFERLEGIERUNG UND HERSTELLUNGSVERFAHREN DAFÜR

Title (fr)
MATÉRIAU EN ALLIAGE DE CUIVRE ET SON PROCÉDÉ DE FABRICATION

Publication
EP 2752498 A1 20140709 (EN)

Application
EP 12828596 A 20120829

Priority
• JP 2011186253 A 20110829
• JP 2012071857 W 20120829

Abstract (en)
{Problems} To provide a copper alloy material that is excellent in bending property, 0.2% yield stress, electrical conductivity, and stress relaxation resistance, and that is suitable in lead frames, connectors, terminal materials, and the like of, for example, parts to be mounted on vehicles and surrounding infrastructures primarily for EVs and HEVs, and solar photovoltaic power generation systems. {Means to solve} A copper alloy material, containing 0.1 to 0.8 mass% of Cr, and 0.01 to 0.5 mass% in total of at least one selected from the group consisting of an additional alloying element group 1 and an additional alloying element group 2 described below, with the balance being copper and unavoidable impurities, wherein in a crystal orientation analysis of a rolled face in an electron backscatter diffraction analysis, the area ratio of grains having an orientation in which a deviation from the Cube orientation {001} <100> is within 15° is 3% or more, and wherein the ratio of coincidence grain boundary £3 in grain boundaries is 20% or more: an additional alloying element group 1: at least one selected from the group consisting of Mg, Ti and Zr in an amount of 0.01 to 0.5 mass% in total; and an additional alloying element group 2: at least one selected from the group consisting of Zn, Fe, Sn, Ag, Si and P in an amount of 0.005 to 0.5 mass% in total.

IPC 8 full level
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CPC (source: EP KR)
C22C 1/10 (2013.01 - KR); **C22C 9/00** (2013.01 - EP KR); **C22C 9/02** (2013.01 - EP); **C22C 9/04** (2013.01 - EP); **C22C 9/10** (2013.01 - EP); **C22F 1/00** (2013.01 - EP); **C22F 1/08** (2013.01 - EP KR); **H01B 1/026** (2013.01 - EP)

Cited by
EP3242299A1; ITUA20163211A1; US10619232B2; US10392680B2; US10522268B2; WO2016124322A1

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